

layers.

45. (New) A computer system comprising:
a processor;
a memory system coupled to the processor, the memory system is on a substrate and comprises a plurality of devices; and
an interconnect system comprising:
a foamed polymer layer having a cell size of less than about .1 microns, the foamed polymer layer on the substrate; and
a plurality of copper structures embedded in the foamed polymer layer, and each of the plurality of conductive structures is capable of interconnecting at least two of the plurality of devices.

REMARKS

Applicant has carefully reviewed and considered the Office Action mailed on July 16, 2001 and the references cited therewith.

No claims are amended, no claims are canceled, and claims 42-45 are added; as a result, claims 1-20 and claims 42-45 are now pending in the application.

§103 Rejection of the Claims

Claims 1-9 and 11-20 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Wojnarowsky [sic] et al. (U.S. Patent No. 5,449,427). Applicant traverses the rejections.

Claims 1, 6, and 12 recite "a surface that is *hydrophobic*." (emphasis added) The Office action cites to the abstract and to column 6, lines 5-10, to support the rejection, but applicant is unable to find the word "hydrophobic" in the cited material or anywhere in the Wojnarowski et al. patent. Therefore, the Office action is rejecting claims 1, 6, and 12 on a single prior art reference that does not include each of the elements of claims 1, 6, and 12. Since not all of the recited elements of claims 1, 6, and 12 are found in Wojnarowski et al., applicant assumes that the Examiner is taking official notice of the missing elements. Applicant respectfully objects to the taking of official notice in a single reference obviousness rejection, and pursuant to M.P.E.P. § 2144.03,

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